

200 Gbps/lane AUI C2M Channel Selection Criteria

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Introduction

- There are complex relationships between the AUI C2M channel characteristics, the AUI C2M BER target, AUI C2M TX/RX complexity, the optical PMD BER target, etc.
- Many AUI C2M channels are available for study via the 3dj TF website as well as through other industry groups
 - Over 100 channels with various assumptions and differing levels of maturity and complexity

Goals

- The goals of this contribution are to:
 - Form several “classes” of reference equalizers for comparison purposes
 - Selectively reduce the number of AUI C2M channels for analysis in order to focus baseline proposal development efforts
 - Provide a relative comparison using COM with these reduced channels
 - Start discussions in the Task Force on which contributed AUI C2M channels should pass versus which should fail
 - Discuss the ones that fall in the middle
- Not debating the C2M specification parameters at this time, including the reference receiver model, package parameters and COM, etc.
 - Please look for the high-level trends, not at the minutiae

Classes of Reference Equalizers

- Various contributions look at different reference equalizers
 - Propose different classes for the relative comparison of performance for *direction finding* purposes
 - Taken from https://www.ieee802.org/3/dj/public/23_03/li_3dj_01a_2303.pdf
- (Mild)
- ↓
- (Spicy!)
- Class I: 802.3ck C2M-like
 - Class II: 802.3ck C2M-like + Floating Taps
 - Class III: 802.3ck CR-like
 - Class IV: 802.3ck CR-like + MLSE
- Note: these classes are starting points, not specific recommendations. We had to start with *something* 😊

Reference EQ Highlights – By Class

- Class I/II/III/VI

Parameter	802.3ck C2M			Exploratory of 802.3dj Medium Loss AUI C2M		Exploratory of 802.3dj High Loss AUI C2M	
	802.3ck C2M	802.3ck CR	802.3ck KR	802.3ck C2M-like	802.3ck C2M-like + FLT	802.3ck CR-like	802.3ck CR-like + MLSE
DER_0	1E-5	1E-4	1E-4	1E-5/5E-5/1E-4	1E-5/5E-5/1E-4	1E-5/5E-5/1E-4	1E-5/5E-5/1E-4
SNR_TX	32.5	32.5	33	32.5	32.5	33	33
R_LM	0.95	0.95	0.95	0.95	0.95	0.95	0.95
TxFIR Length	4 (2 pre)	5 (3 pre)	5 (3 pre)	5 (3 pre)	5 (3 pre)	6 (4 pre)	6 (4 pre)
eta_0	4.10E-08	9E-09	8.2E-09	2.05E-08	2.05E-08	4.1E-09	4.1E-09
N_b	4	12	12	8	8	24	24
N_bg	0	3	3	0	3	6	6
N_bf	-	3	3	3	3	3	3
N_f	-	40	40	80	80	80	80
MLSE	0	0	0	0	0	0	1
Ref TX/RX Class				I	II	III	VI

(Mild)

(Spicy!)

Note: these classes are starting points,
not specific recommendations.

https://www.ieee802.org/3/dj/public/23_03/li_3dj_01a_2303.pdf

Reducing the # of Channels

- Across the inventory of AUI C2M channels available, we attempted to reduce the total number of channels down to ~10-15 unique, representative channels
 - Decrease analysis time
 - Assess the outliers
 - Eliminate obviously bad channels
- Channel parameters that we used include: Fit IL, ERL, ICN, ICR

802.3dj C2M Channel Contributions

Contribution	Channel List	Host Type
akinwale_3df_01_2209 (21x)	C2M_PCB_85ohms_10~30dB_202208016_v2_thru1	CONV PCB
akinwale_3df_02_2209 (21x)	C2M_PCB_93ohms_10~30dB_202208016_v2_thru1	CONV PCB
akinwale_3df_03_2209 (21x)	C2M_PCB_100ohms_10~30dB_202208016_v2_thru1	CONV PCB
rabinovich_3df_01_2209 (3x) rabinovich_3dj_02_230116 (1x)	Rabinovich_C2M_200G_Ortho_[19, 67, 93]mil_092122_Thru.s4p Rabinovich_C2M_200G_Ortho_135mil_011723_Thru.s4p	CONV PCB
rabinovich_3df_02_2209 (3x) rabinovich_3dj_03_230116 (1x)	Rabinovich_C2M_200G_Paral_[19, 67, 93]mil_092122_Thru.s4p Rabinovich_C2M_200G_Paral_135mil_011723_Thru.s4p	CONV PCB
	TE_224G_C2M_Conventional_[5,7,13]inHst_100622_THRU.s4p	CONV PCB
tracy_3df_02_2211	TE_224G_C2M_NCC_100622_THRU.s4p	NCC
	TE_224G_C2M_CPC_CPB_091622_THRU_mod.s4p	CPC

Extreme impedance corners
(not included at this time)

Technology still stabilizing
(not included at this time)

<https://www.ieee802.org/3/df/public/tools/index.html>

Expanded List of Channels

Fit IL (dB)	<= 16	16 < X <= 28	> 28
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	Max	Q3	Med	Q1	MIN
ERL	19.19	13.46	12.79	12.02	10.29

Challenge	Channel	IL (dB)	Fit IL (dB)	FOM_ILD (dB)	ERL (DER 0 = 1E-5)	ICN (mV)	ICR (dB)
Reflection	akinwale_3df_02_2209/C2M_PCB_93ohms_10dB	8.77	10.35	0.53	11.33	2.55	26.96
Reflection	akinwale_3df_02_2209/C2M_PCB_93ohms_11dB	9.61	11.22	0.52	11.56	2.32	27.72
Reflection	akinwale_3df_02_2209/C2M_PCB_93ohms_12dB	10.45	12.07	0.52	11.80	2.11	27.11
Reflection	akinwale_3df_02_2209/C2M_PCB_93ohms_13dB	11.31	12.92	0.52	12.02	1.93	27.58
Reflection	akinwale_3df_02_2209/C2M_PCB_93ohms_14dB	12.17	13.83	0.55	11.48	1.91	26.96
Reflection	akinwale_3df_02_2209/C2M_PCB_93ohms_15dB	13.03	14.67	0.56	11.68	1.76	27.07
Reflection	akinwale_3df_02_2209/C2M_PCB_93ohms_16dB	14.73	16.33	0.57	12.03	1.50	26.75
Reflection	akinwale_3df_02_2209/C2M_PCB_93ohms_17dB	15.55	17.16	0.58	12.18	1.40	26.63
	akinwale_3df_02_2209/C2M_PCB_93ohms_18dB	16.42	17.98	0.59	12.33	1.30	26.28
	akinwale_3df_02_2209/C2M_PCB_93ohms_19dB	17.24	18.80	0.60	12.46	1.22	26.20
	akinwale_3df_02_2209/C2M_PCB_93ohms_20dB	18.11	19.62	0.61	12.59	1.15	25.65
	akinwale_3df_02_2209/C2M_PCB_93ohms_21dB	19.80	21.25	0.64	12.80	1.04	24.85
	akinwale_3df_02_2209/C2M_PCB_93ohms_22dB	20.63	22.06	0.65	12.89	0.99	24.66
	akinwale_3df_02_2209/C2M_PCB_93ohms_23dB	21.49	22.87	0.66	12.98	0.95	23.87
	akinwale_3df_02_2209/C2M_PCB_93ohms_24dB	22.33	23.68	0.68	13.06	0.92	23.57
	akinwale_3df_02_2209/C2M_PCB_93ohms_25dB	24.02	25.29	0.70	13.21	0.86	22.29
	akinwale_3df_02_2209/C2M_PCB_93ohms_26dB	24.87	26.09	0.72	13.27	0.84	21.46
	akinwale_3df_02_2209/C2M_PCB_93ohms_27dB	25.71	26.89	0.73	13.33	0.83	20.89
	akinwale_3df_02_2209/C2M_PCB_93ohms_28dB	26.56	27.70	0.74	13.38	0.81	20.06
IL, Xtalk	akinwale_3df_02_2209/C2M_PCB_93ohms_29dB	28.25	29.30	0.76	13.49	0.79	18.57
IL, Xtalk	akinwale_3df_02_2209/C2M_PCB_93ohms_30dB	29.10	30.11	0.78	13.53	0.78	17.83
	Rabinovich_C2M_200G_Ortho_19mil_092122	12.38	13.57	0.70	18.06	1.79	28.68
	Rabinovich_C2M_200G_Ortho_67mil_092122	14.70	14.87	0.69	17.50	2.71	27.00
	Rabinovich_C2M_200G_Ortho_93mil_092122	14.17	14.81	0.95	15.36	2.83	24.90
Xtalk	Rabinovich_C2M_200G_Ortho_135mil_011723	13.35	14.99	0.96	15.20	3.39	22.24
	Rabinovich_C2M_200G_Paral_19mil_092122	12.27	13.16	0.47	18.30	2.35	26.93
	Rabinovich_C2M_200G_Paral_67mil_092122	13.32	13.91	0.50	17.90	2.87	26.79
Xtalk	Rabinovich_C2M_200G_Paral_93mil_092122	13.44	14.12	0.67	14.98	3.17	24.32
Xtalk	Rabinovich_C2M_200G_Paral_135mil_011723	12.93	14.44	0.49	15.51	3.78	22.23
	tracy_3df_02_2211_C2M_CONV_5p4dB_HOST	10.26	10.64	0.55	18.76	1.58	45.15
	tracy_3df_02_2211_C2M_CONV_7p6dB_HOST	12.36	12.79	0.56	18.94	1.24	46.47
	tracy_3df_02_2211_C2M_CONV_14dB_HOST	18.78	19.18	0.62	19.19	0.64	49.12
	tracy_3df_02_2211_C2M_NCC_HOST	10.43	11.09	0.41	15.27	2.28	28.52

- This presentation does not intend to propose any channel specifications
- The relative ERL, ICN, and ICR are compared under largely channel commonality:
 - OSFP connector (possibly from the same contributor)
 - Host type: CONV PCB (except one is NCC)

Package loss is ~7dB per 30mm, ~9dB total for 30mm+8mm.
 Source: https://www.ieee802.org/3/df/public/22_11/benartsi_3df_01a_2211.pdf

Relative COM Comparison with Proposed Channels

- The assumed AUI C2M BER targets were 1E-5, 2E-5, 5E-5, 8E-5
 - Much less interest in 1E-4
- Of course, the reported COM results will change depending on the channel, Cd, Cp, host and module package trace lengths, reference receiver model architecture & settings, etc.
- One package scenario: 30mm + 8mm (~9 dB IL)

Straw Poll #1 and 2 -- directional

At this time, I prefer the 200 Gbps/lane AUI BER target option per brown_3dj_elec_01_230420 slide 18:

- Option A: C2M and C2C AUI BER 1E-5
- Option B: C2M and C2C AUI BER 2E-5
- Option C: C2M and C2C AUI BER 5E-5
- Option D: C2M and C2C AUI BER 1E-4
- Option E: C2M AUI BER 8E-5 and C2C AUI BER 2E-5

SP#1 Results (Chicago rules): A: 29 B: 19 C: 25 D: 8 E: 24

SP#2 Results (Choose one): A: 12 B: 4 C: 17 D: 0 E: 12 NMI: 11

https://www.ieee802.org/3/dj/public/adhoc/electrical/23_0420/straw_polls_3df_elec_adhoc_230420.pdf

A Relative Comparison

Fit IL (dB)	<= 16	16 < X <= 28	> 28		Max	Q3	Med	Q1	MIN	
COM (dB)	>= 3.5	2.5 <= X < 3.5	< 2.5		ERL	19.19	13.46	12.79	12.02	10.29

Challenge	Channel	IL (dB)	Fit IL (dB)	FOM_ILD (dB)	ERL (DER_0 = 1E-5)	ICN (mV)	ICR (dB)	COM (DER_0 = 1E-5, 30mm/8mm)				COM (DER_0 = 5E-5, 30mm/8mm)				COM (DER_0 = 1E-4, 30mm/8mm)				
								I	II	III	IV	I	II	III	IV	I	II	III	IV	
Reflection	akinwale_3df_02_2209/C2M_PCB_93ohms_10dB	8.77	10.35	0.53	11.33	2.55	26.96													
Reflection	akinwale_3df_02_2209/C2M_PCB_93ohms_11dB	9.61	11.22	0.52	11.56	2.32	27.72													
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Xtalk	Rabinovich_C2M_200G_Paral_93mil_092122	13.44	14.12	0.67	14.98	3.17	24.32													
Xtalk	Rabinovich_C2M_200G_Paral_135mil_011723	12.93	14.44	0.49	15.51	3.78	22.23													
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Medium Loss AUI
C2M Candidates

These channels need more equalization (class III or better) than the others

High Loss AUI
C2M Candidates

These channels could work with a Medium complexity Equalizer (class I-II)

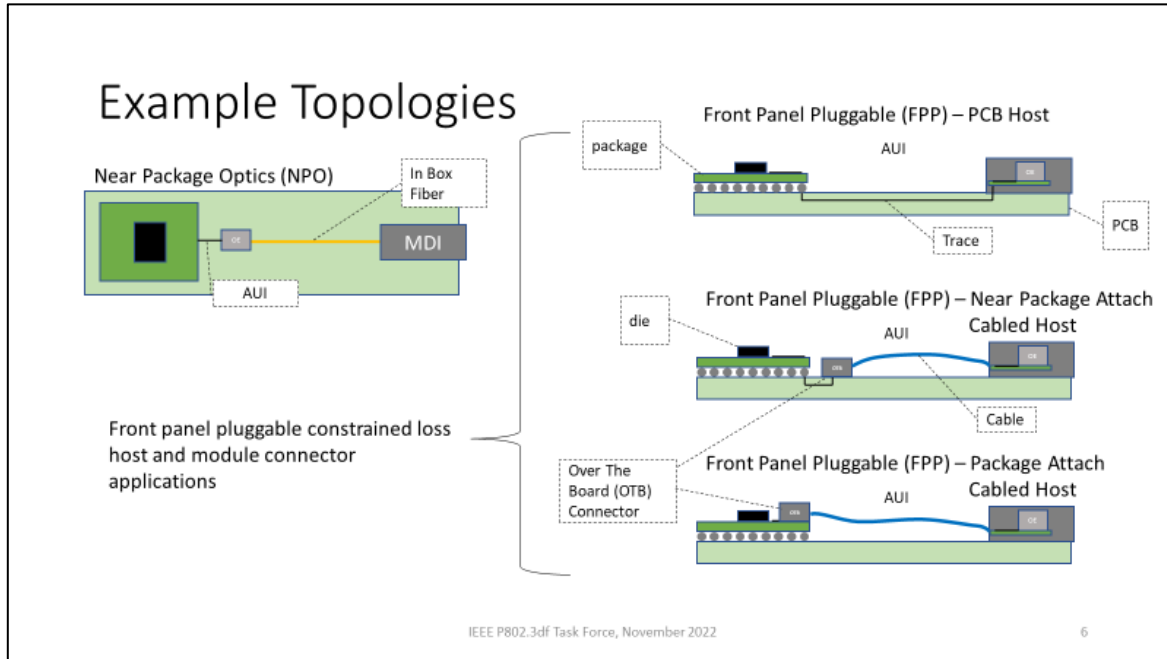
Medium Loss AUI
C2M Candidates

- This presentation does not intend to propose any channel specifications
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 - Host type: CONV PCB (except one is NCC)

Package loss is ~7dB per 30mm, ~9dB total for 30mm+8mm.
Source: https://www.ieee802.org/3/df/public/22_11/benartsi_3df_01a_2211.pdf

AUI C2M Loss Reminder

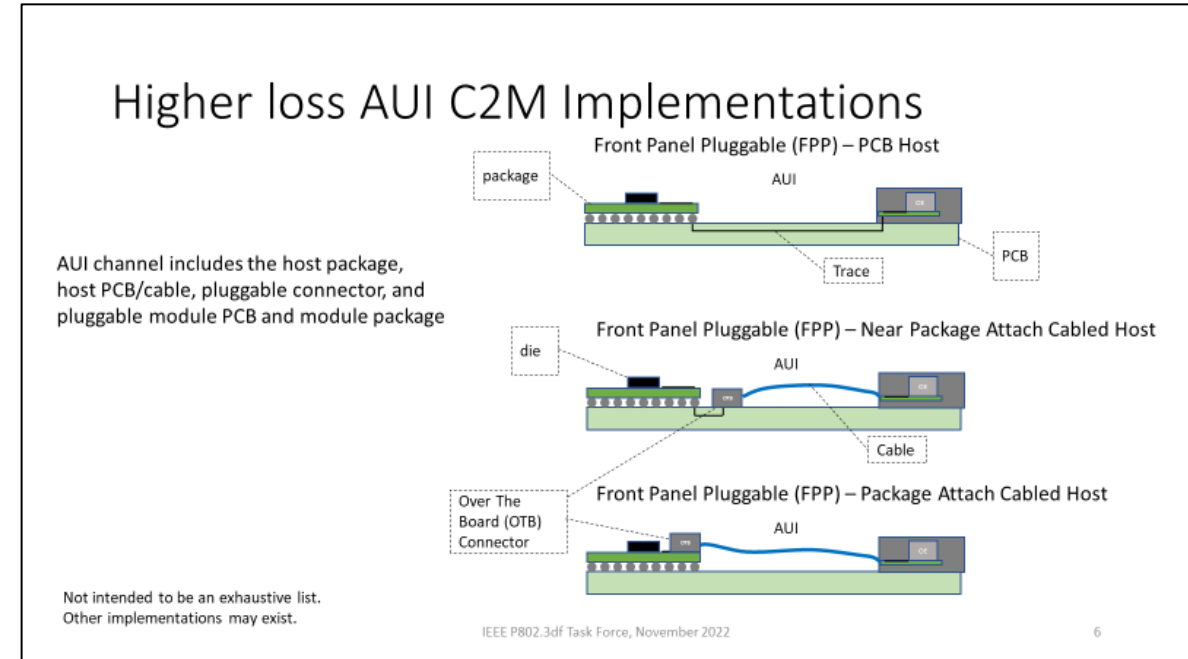
Medium Loss AUI C2M



- Targets ~22 dB IL die-die
- NPO and constrained loss FPP
- The COM reference transmitter and receiver models and parameters are an evolution from 3ck, scaled to the higher signaling rate

https://www.ieee802.org/3/df/public/22_11/lusted_3df_03a_2211.pdf

High Loss AUI C2M



- Targets ~36 dB IL die-die
- Primarily FPP
- Reference receiver and transmitter models leveraged from 3ck backplane and copper cable, scaled appropriately

https://www.ieee802.org/3/df/public/22_11/lusted_3df_02_2211.pdf

Summary

- Established several “classes” of reference equalizers for relative comparison purposes
 - “Mild” (Class I) to “spicy” (Class IV)
- Selectively reduced the number of AUI C2M channels for analysis in order to focus baseline proposal development efforts
- Provided a relative comparison using COM with these reduced channels
 - Some channels work with medium complexity equalization assumed for medium loss AUI C2M
 - Almost all channels work with higher complexity equalization assumed for high loss AUI C2M
- Next step is to recommend a pass/fail grading for the reduced channels, by AUI C2M loss category
 - Plan to have initial grading for the May 2023 interim meeting
 - Please reach out to us to get involved in the proposed grading

Thanks!

BACKUP

COM Reference Sheets for Class I/II/III/VI

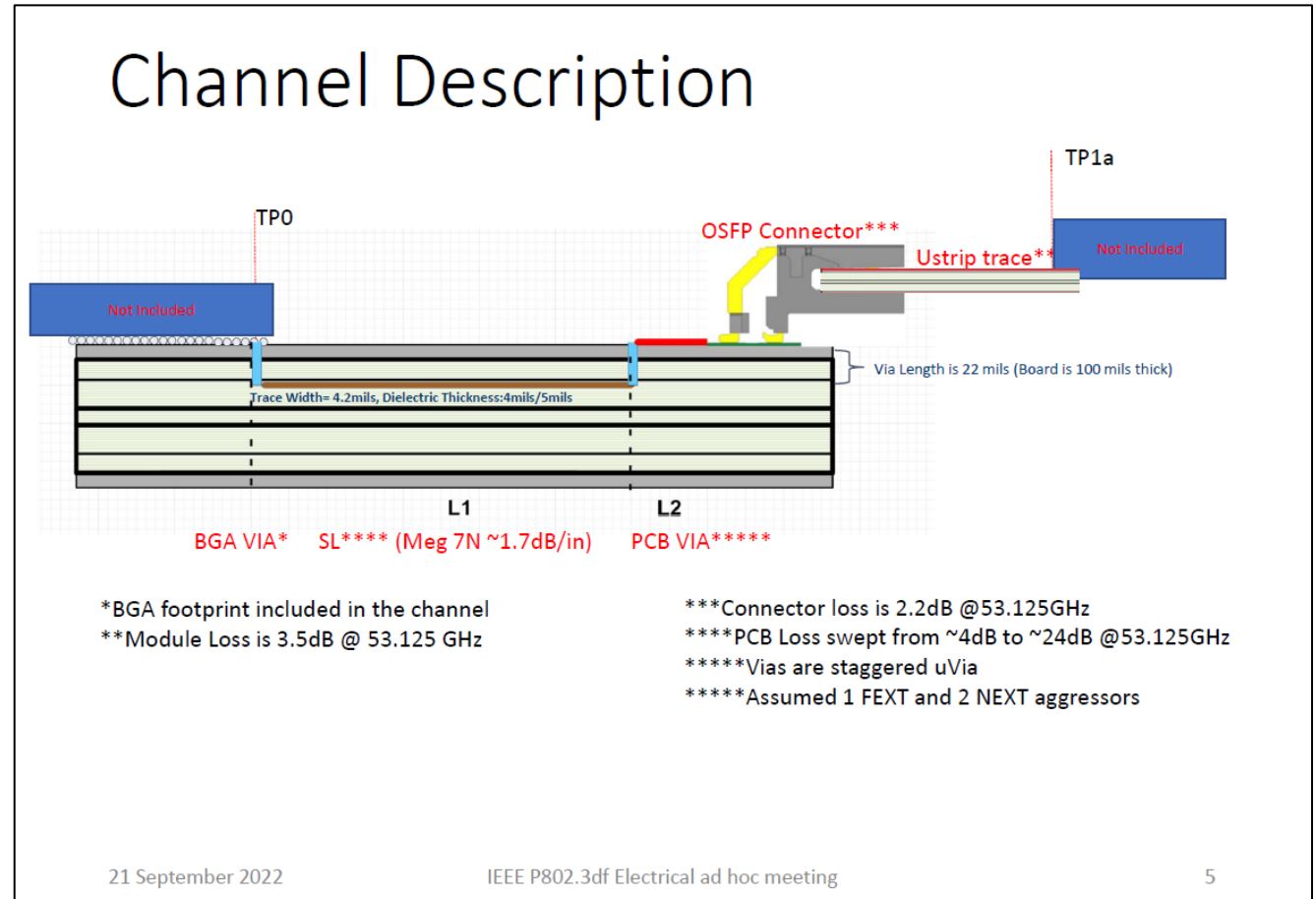
Table 93A-1 parameters				I/O control			Table 93A-3 parameters		
Parameter	Setting	Units	Information				Parameter	Setting	Units
f_b	106.25	Gbd		DIAGNOSTICS	0	logical	package_tl_gamma0_a1_a2	[0 0.0008455 0.000340225]	
f_min	0.05	GHz		DISPLAY_WINDOW	0	logical	package_tl_tau	0.00644805	ns/mm
Delta_f	0.01	GHz		RESULT_DIR	.\results\CAKR_[date]\		package_Z_c	[92 92 ; 70 70; 80 80; 100 100]	Ohm
C_d	[0.4e-4 0.9e-4 1.1e-4 0.4e-4 0.9e-4 1.1e-4]	nF	[TX RX]	SAVE_FIGURES	0	logical			
L_s	[0.13 0.15 0.14; 0.13 0.15 0.14]	nH	[TX RX]	Port Order	[1 3 2 4]				
C_b	[0.3e-4 0.3e-4]	nF	[TX RX]	RUNTAG	CAKR_RCos_eval				
z_p select	[1 2]		[test cases to run]	COM_CONTRIBUTION	0	logical			
z_p (TX)	[15 30; 11 ; 11 ; 0.5 0.5]	mm	[test cases]	Operational			board_tl_gamma0_a1_a2	[0 6.44084e-4 3.6036e-05]	1.5 db/in @ 56G
z_p (NEXT)	[8 8; 0 0; 0 0; 0 0]	mm	[test cases]	ERL Pass threshold	10	dB	board_tl_tau	5.790E-03	ns/mm
z_p (FEXT)	[15 30; 11 ; 11 ; 0.5 0.5]	mm	[test cases]	COM Pass threshold	3	db	board_Z_c	100	Ohm
z_p (RX)	[8 8; 0 0; 0 0; 0 0]	mm	[test cases]	DER_0	1.00E-04		z_bp (TX)	125	mm
PKG_Tx_FFE_preset	0			T_r	3.75E-03	ns	z_bp (NEXT)	0	mm
C_p	[0.5e-4 0.5e-4]	nF	[TX RX]	FORCE_TR	1	logical	z_bp (RX)	0	mm
R_0	50	Ohm		PMD_type	C2C		C_0	[0.2e-4 0]	nF
R_d	[50 50]	Ohm	[TX RX]	EW	1		C_1	[0.2e-4 0]	nF
A_v	0.413	V	vp/vf=	* TDR and ERL options			Include PCB	0	logical
A_fe	0.413	V	vp/vf=	TDR	1	logical			
A_ne	0.45	V	vp/vf=	ERL	1	logical			
L	4			ERL_ONLY	0	ns	Selections (rectangle, gaussian dual rayleigh, triangle)		
M	32			TR_TDR	0.01		Histogram_Window_Weight	gaussian	selection
filter and Eq				N	800	logical	Qr	0.02	UI
f_r	0.75	fb		TDR Butterworth	1				
c(0)	0.54		min	beta_x	0		* ICN parameters		
c(-1)	[-0.34;0.02;0]		[min:step:max]	rho_x	0.618		f_v	0.594	Fb
c(-2)	[0.02;0.12]		[min:step:max]	TDR_W_TXPKG	0	UI	f_f	0.594	Fb
c(-3)	[-0.06; 0.02;0]		[min:step:max]	N_bx	8		f_n	0.594	Fb
c(-4)	[0.02;0.04]		[min:step:max]	fixture delay time	[0 0]		f_2	79.688	GHz
c(1)	[-0.12;0.02;0.1]		[min:step:max]	Tukey Window	1		A_ft	0.450	V
N_b	24	UI		Noise, jitter			A_nt	0.450	V
b_max(1)	0.85		As/dfe1	sigma_RJ	0.01	UI			
b_max(2..N_b)	[0.5 0.3 0.3 0.2*ones(1,20)]		As/dfe2..N_b	A_DD	0.02	V^2/GHz	Floating Tap Control		
b_min(1)	0.3		As/dfe1	eta_0	4.10E-09	dB	N_bg	6	0 1 2 or 3 groups
b_min(2..N_b)	[0.2 0.05 0.05 -0.05*ones(1,20)]		As/dfe2..N_b	SNR_TX	33		N_bf	3	taps per group
g_DC	[-20;1.0]	dB	[min:step:max]	R_LM	0.95		N_f	80	UI span for floating taps
f_z	42.5	GHz		Enforce Causality			bmaxg	0.2	max DFE value for floati
f_p1	42.5	GHz		S-parameter magnitude extrapol	trend_to_DC				
f_p2	106.25	GHz		MLSE	1	logical	Receiver testing		
g_DC_HP	[-6;1.0]		[min:step:max]				RX_CALIBRATION	0	logical
f_HP_PZ	1.328125	GHz					Sigma BBN step	5.00E-03	V
Butterworth	1	logical	include in fr						
Raised_Cosine	0	logical	include in fr						

*ERL and ICN parameters

** Make changes of Class I/II/III/VI based on parameters listed in slide 6

C2M Channel Summaries (1/3)

- TP0 to TP1a IL range from 10.35dB to 29.56dB in two different model variants
 - Host PCB length
 - Host PCB impedance



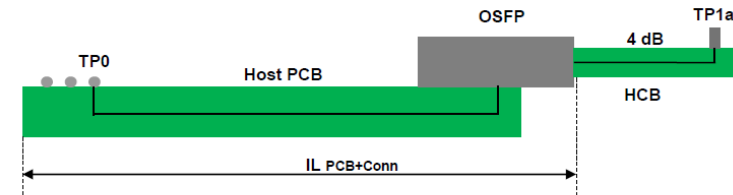
Contribution: [akinwale_3df_elec_01_220921](#)
Channel: [akinwale_3df_01_2209](#), [akinwale_3df_02_2209](#),
[akinwale_3df_03_2209](#)

C2M Channel Summaries (2/3)

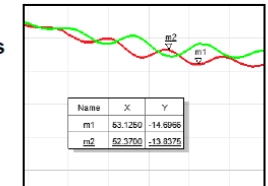
- TP0 to TP1a IL range from 10.64dB to 14.99dB in two different model variants
 - ASIC breakout topology
 - Via length

200G PAM4 C2M Via Length Effect Study

Structure View & Insertion Losses



- Full Structure:
 - Two adjacent channels
 - Matching segmentation meshing (i.e., common minimum element size)
 - Connector integrated with PCB
 - HCB is ideal transmission line with IL = 4 dB @ Nyquist
 - NEXT is evaluated at the ASIC model for more realistic results
- Vias = 19/67/93 mil long
- Blind Vias
- Frequency Sweep Range = 10 MHz to 120 GHz



IL @ Nyquist (53.125 GHz)

Parallel Breakout

- IL PCB+Conn = 8.24/9.32/10.31 dB
- IL HCB = 4 dB
- IL TP0-to-TP1a = 12.27/13.32/13.44 dB

Orthogonal Breakout

- IL PCB+Conn = 8.34/10.69/10.14 dB
- IL HCB = 4 dB
- IL TP0-to-TP1a = 12.38/14.69/14.17 dB

Reflections Effect

Contribution: [rabinovich_3df_elec_01b_220921](#),
[rabinovich_3dj_01_230116](#)

Channel: [rabinovich_3df_01_2209](#), [rabinovich_3df_02_2209](#),
[rabinovich_3dj_02_230116](#), [rabinovich_3dj_03_230116](#)

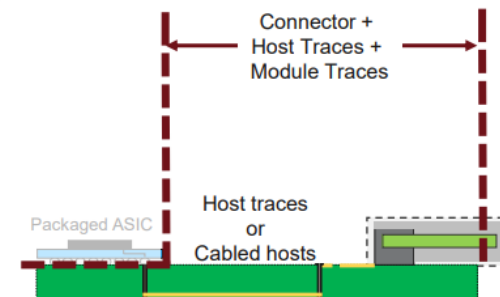


C2M Channel Summaries (3/3)

- TP0 to TP1a IL range from 7.54dB to 19.18dB in two different model variants
 - Host type
 - Host PCB length

Description

- Simulation for 200G chip to module channels using concept connector with various host architecture options
- Includes BGA escape model provided by Regee Petaja of Broadcom
- Does NOT include silicon package
- Current view of Chip to Module performance in various host implementations
- What this presentation is NOT:
 - Modulation proposal
 - Channel or host loss proposal
 - Compliance board proposal
 - A specific host architecture proposal;
 - comparative performance options are presented, i.e., traces vs. cabled host to “near ASIC” vs. co-package copper
 - Asymmetric architectures (managed deployment)



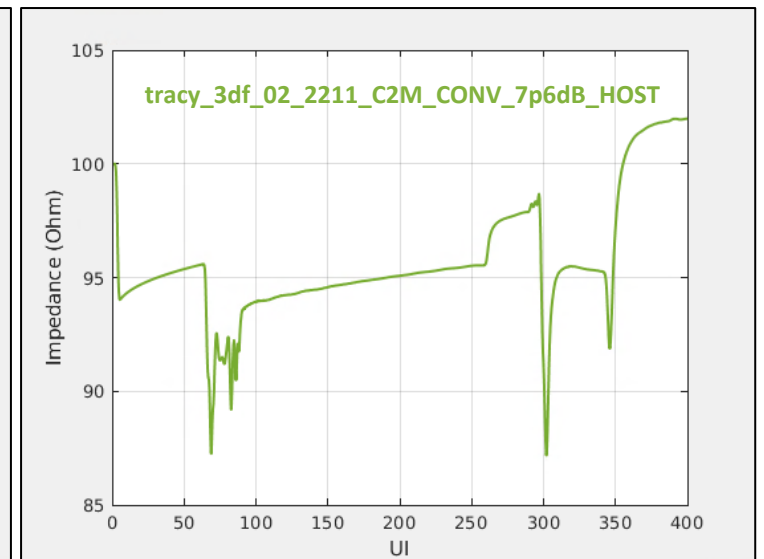
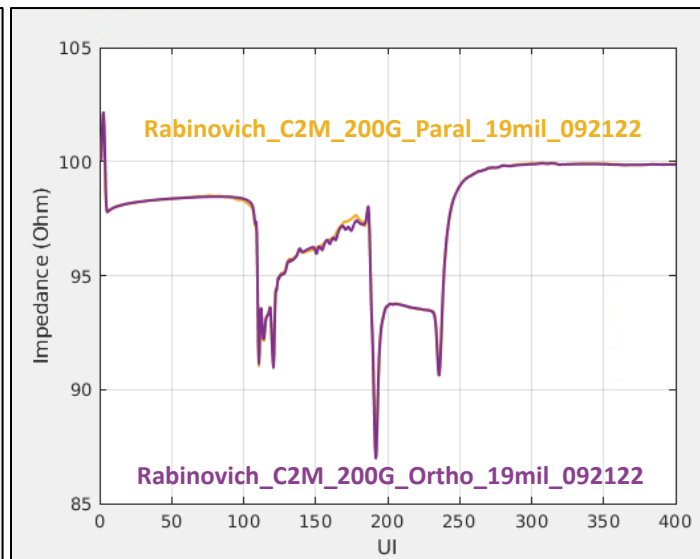
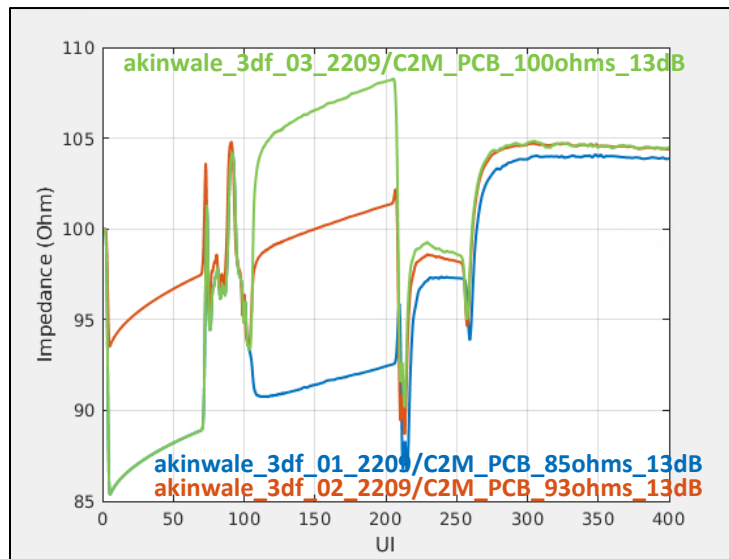
5

Contribution: [tracy_3df_02_2211](#)

Channel: [tracy_3df_02_2211_sparameters](#)

Coarse Selection via Impedance Corner

- TP1a-die (host) TDR
 - Impedance mismatch among MCB-Conn-HCB in **akinwale_3df_01_2209 (85Ohm)** and **akinwale_3df_03_2209 (100Ohm)** are greater than **10%**



Two AUI C2M Host Losses

Straw Poll #1

For the front panel pluggable use case, I am interested in 200 Gbps/lane AUI C2M specifications for:

- A. medium loss only (e.g. up to ~22 dB IL die-die per lusted_3df_01_220927)
- B. higher loss only (e.g. up to ~36 dB IL die-die per lusted_3df_01_220927)
- C. both medium and higher loss
- D. need more information

pick one

Results: A: 17, B: 11, C: 49, D: 12

https://www.ieee802.org/3/df/public/22_10/motions_3df_221004.pdf